

**SUPPORTING STRUCTURE FOR A CHIP AND METHOD FOR PRODUCING
THE SAME**

ABSTRACT

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A supporting structure for a chip includes a supporting substrate with a bond opening therein and an interconnect layer on the supporting substrate. In the interconnect layer, a bonding channel overlapping with the bond opening 10 is formed. The supporting structure further includes an escape prevention structure for the bonding channel to enable escaping of air from the bonding channel and to prevent the encapsulation material from escaping from the bonding channel on introducing encapsulation material into 15 the bonding channel after the applying of a chip to the supporting structure.